A method of forming an integrated circuit, including providing a first, substrate layer having a center piece and two side pieces on opposite sides of the center piece, assembling one or more circuit elements on a top side and a bottom side of the center piece of the first substrate layer, preparing two support pieces from a substrate, matching the size of the side pieces, coupling the support pieces to the bottom of the first substrate layer under the side pieces to form a second substrate layer with a void in the center under the center piece of the first substrate layer; and wherein the side pieces and support pieces include via connectors electrically connecting between a bottom side of the second substrate layer and the circuit elements.

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